

IN THE CLAIMS:

Claims 1-19 and 29-34 were previously cancelled pursuant to an Examiner's Amendment. Claims 20 through 28 have been amended herein. All of the pending claims are presented below. This listing of claims will replace all prior versions and listings of claims in the application. Please enter these claims as amended.

Listing of Claims:

1.-19. (Cancelled)

20. (Currently amended) A method for fabricating a semiconductor card, comprising: providing a strip comprising a module with a peripheral opening defining an internal substrate and an external frame, and a plurality of connecting segments connecting the substrate to the frame, the substrate comprising a circuit side having a circuit thereon and a back side having external contacts thereon; mounting at least one semiconductor component to the circuit side in electrical communication with the external contacts; installing the strip in a molding assembly having a molding cavity with internal surfaces in first and second mold plates and wherein the substrate is forcibly moved to a level differing from the level of the frame; molding a plastic body on the circuit side of the substrate, ~~said- the~~ body including edge portions of the card formed laterally outwardly from the substrate, and a plurality of wings extending laterally outwardly from ~~said- the~~ edge portions; and removing the molded casting from the molding assembly and singulating the card from the wings by excision.

21. (Currently amended) ~~A- The~~ method in accordance with claim 20, wherein the substrate is moved to a level at which the back side thereof abuts a surface of the molding cavity.

22. (Currently amended) ~~A-~~ The method in accordance with claim 20, wherein said the substrate is moved a distance of about 0.2 - 3 times the substrate thickness.

23. (Currently amended) ~~A-~~ The method in accordance with claim 20, wherein said the substrate is moved by movement of pins passing through down-set throughholes in said the molding assembly and wings to contact, move and clamp the connecting segments attached to the substrate.

24. (Currently amended) ~~A-~~ The method in accordance with claim 20, wherein portions of said the peripheral opening adjacent the outer outer ends of said the connecting segments are elongated laterally outward to lengthen said the connecting segments.

25. (Currently amended) ~~A-~~ The method in accordance with claim 20, wherein said the frame is connected by connecting segments to the substrate on opposing edges thereof.

26. (Currently amended) ~~A-~~ The method in accordance with claim 20, wherein said the molding step encapsulates the circuit side of the substrate and leaves the external contacts uncovered.

27. (Currently amended) ~~A-~~ The method in accordance with claim 23, wherein the molded casting is removed from the molding assembly by inserting pins into the down-set throughholes to eject the molding molded casting thereby.

28. (Currently amended) ~~A-~~ The method in accordance with claim 23, wherein the molded casting is removed from the molding assembly by further insertion of the down-set pins through the down-set throughholes to eject the molding molded casting thereby.

29.-34. (Cancelled)